

FEATURES

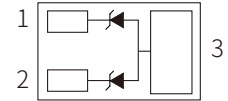
- | 60W Peak Pulse Power per Line (tp=8/20μs)
- | Working voltages : 5 V
- | Low leakage current

APPLICATIONS

- | Cell Phone Handsets and Accessories
- | Microprocessor based equipment
- | Personal Digital Assistants (PDA' s)
- | Notebooks, Desktops, and Servers
- | Video Graphics Cards
- | USB 3.0/USB3.1 Interfaces
- | HDMI 1.4/HDMI 2.0 Interfaces



DFN1006P3



Schematic Symbol

IEC COMPATIBILITY

- | IEC61000-4-2 (ESD) ±20kV (air), ±20kV (contact)
- | IEC61000-4-4 (EFT) 40A (5/50ns)

APPROVALS

- RoHS** | Compliance with 2011/65/EU
- HF** | Compliance with IEC61249-2-21:2003

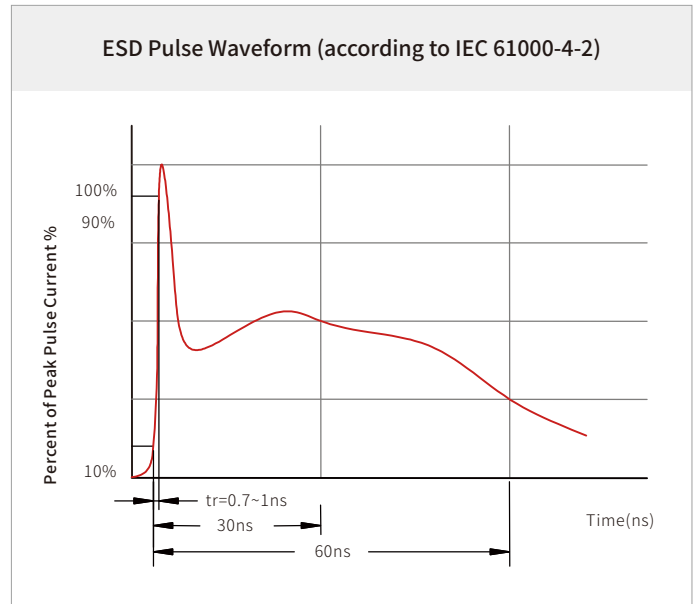
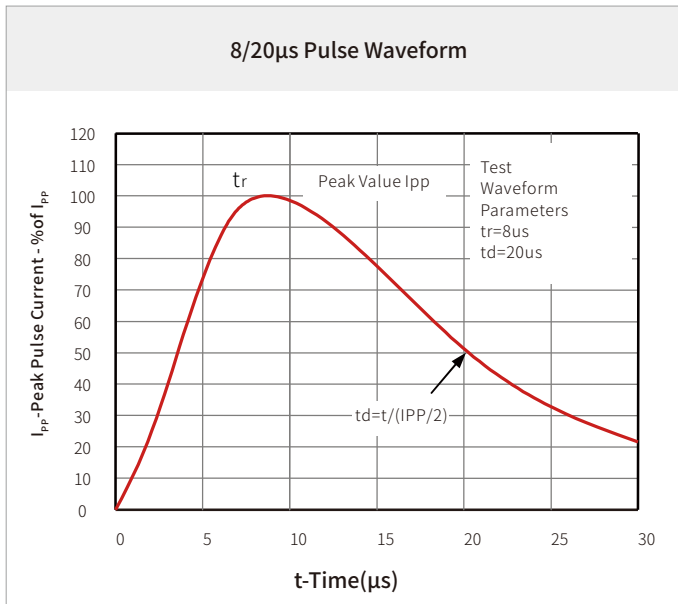
THERMAL CONSIDERATIONS

Symbol	Parameter	Value	Unit
P_{PP}	Peak Pulse Power (tp=8/20μs waveform)	60	Watts
T_J	Operating Temperature Range	-55 to +150	°C
T_{STG}	Storage Temperature Range	-55 to +150	°C

ELECTRICAL CHARACTERISTICS

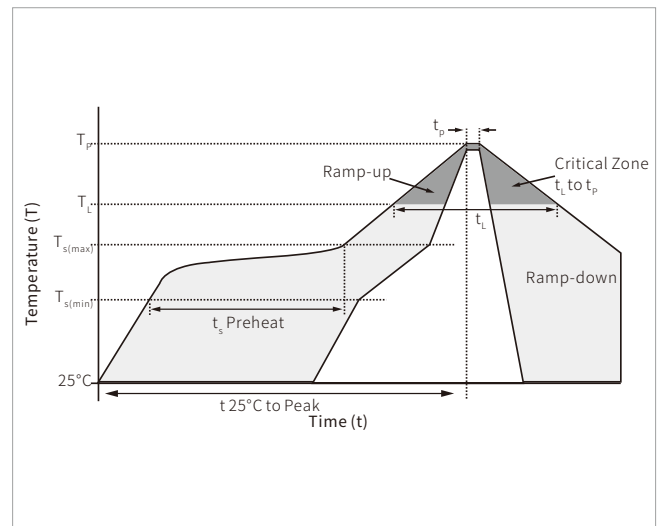
Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V_{RWM}	Reverse Stand-off Voltage				5	V
V_{BR}	Reverse Breakdown Voltage	$I_T=1mA$	6			V
I_R	Reverse Leakage Current	$V_{RWM}=5V$			1	μA
V_C	Clamping Voltage	$I_{PP}=1A, tp=8/20\mu s$			12	V
V_C	Clamping Voltage	$I_{PP}=5.5A, tp=8/20\mu s$			10	V
I_{PP}	Peak Pulse Current	tp=8/20μs			5.5	A
C_J	Off State Junction Capacitance	$V_R=0V, f=1MHz$			15	pF

CHARACTERISTIC CURVES

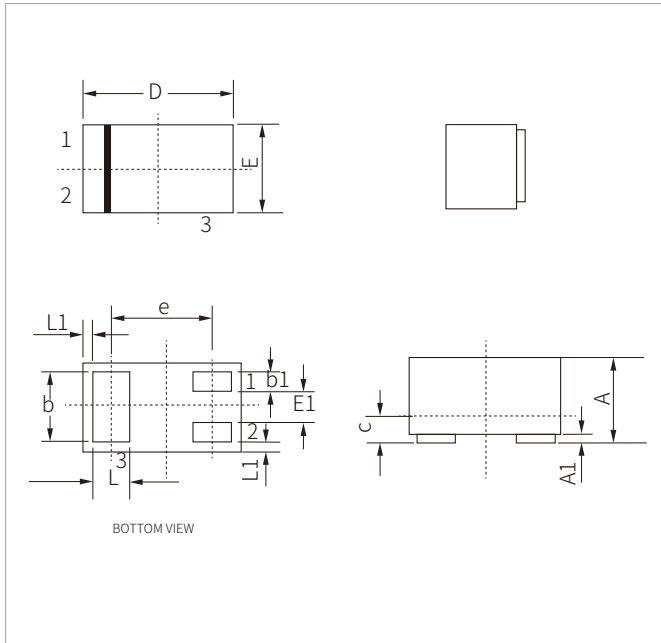


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

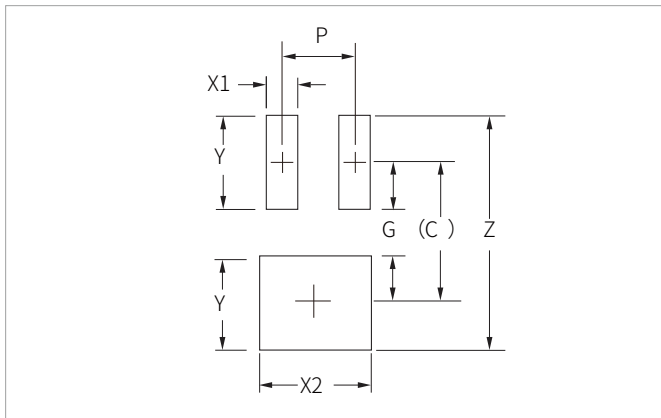


DFN1006P3 PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.35	0.50	0.014	0.020
A1	0	0.05	0	0.002
b	0.45	0.55	0.018	0.022
b1	0.10	0.20	0.004	0.008
c	0.12	0.18	0.005	0.007
D	0.95	1.05	0.037	0.041
e	0.65BSC		0.026BSC	
E	0.55	0.70	0.022	0.027
E1	0.20	0.30	0.008	0.014
L	0.20	0.30	0.008	0.012
L1	0.05REF		0.002REF	

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters	Inches
C	(0.85)	(0.033)
P	0.40	0.016
G	0.30	0.012
X1	0.20	0.008
X2	0.60	0.024
Y	0.55	0.022
Z	1.40	0.055

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SE10P3F06U5.0B	DFN1006P3	10000PCS	7"

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